



洲光源
CHAULIGHT

产品规格书 SPECIFICATION

客户名称: _____

Customer Name

产品类型: 红外光电传感器

Product Name

产品型号: ZOS-R3227-S17-TR8

Part No.

| | | | | | |
|---|------------|---|-----------------------------|--|--|
| <input type="checkbox"/> 技术参考 Technical Reference | | <input type="checkbox"/> 样品 Sample | | <input type="checkbox"/> 量产供货 Mass Product | |
| 客户审核 (加盖公章) Client approval (Stamp) | | | 洲光源审核 Chaulight approval | | |
| 核准 Approval | 确认 Checked | 核准 Approval | 确认 Checked | 制作 Edited | |
| | | 黄瑞良 | 郝三强 | 谢育国 | |
| <input type="checkbox"/> 接收 Qualified | | <input type="checkbox"/> 不接收 Disqualified | | 日期 Date: 2022.04.06 | |

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广东洲光源红外半导体有限公司
Guangdong Chaulight Infrared Semiconductor Co.,Ltd.

ZOS-R3227S17-TR8 是一种光反射开关，包括砷化镓红外-LED 发射机和 NPN 光晶体管，短距离高光敏接收器，在红外范围内工作。这两个组件都是并排安装在一个塑料包装盒中的

ZOS-R3227-S17-TR8 is a light reflection switch that includes arsenide infrared-LED transmitter and NPN phototransistor, short range high photosensitive receiver operating in the infrared range. Both components are mounted side by side in a plastic packing box



特性 Feature

- 快速响应时间
Quick response time
- 高灵敏度
high sensitivity
- 截止可见波长 940nm
The visible wavelength is cut off $\lambda_p=940\text{nm}$
- 无铅材料、Rosh 认证
Pb.Free、RoHS compliant version

应用 Application

- 摄影机 Camera
- 录像机 VCR
- 软盘驱动程序
Floppy disk driver
- 盒式录音机
Cassette type recorder
- 各种微机控制设备
Various microcomputer control equipment

| Device No. | Chip Material |
|------------|---------------|
| IR | GaAs |
| PT | Silicon |

设备选择指南

Device Selection Guide

最大额定值 Absolute Maximum Ratings

| 测试项目 Parameter (Ta=25°C) | 符合 Symbol | 范围 Ratings | 单位 Unit |
|-----------------------------------|-------------------------------------|--------------------|---------|
| 输入端发射极 Input Emitter | 最大功率 Power Dissipation *1 | Pd | 75 mW |
| | 最大反向电压 Reverse Voltage | V _R | 5 V |
| | 最大持续正向电流 Forward Current | I _F | 50 mA |
| | 最大脉冲正向电流 Peak Forward Current *2 | I _{FP} | 1 A |
| 输出端接收极 Output Detector | 最大功率 Power Dissipation *1 | Pd | 75 mW |
| | 集电极-发射极电压 Collector-Emitter Voltage | V _{CEO} | 30 V |
| | 发射极-集电极电压 Emitter-Collector Voltage | V _{ECO} | 5 V |
| | 集电极电流 Collector Current | I _{C(ON)} | 50 mA |
| 工作温度 Operating Temperature | Topr | -20~+70 | °C |
| 储存温度 Storage Temperature | Tstg | -30~+80 | °C |
| 焊接温度 Lead Soldering Temperature*3 | Tsol | 260 | °C |

*1、在 25 摄氏度的环境中测试 below 25 Free Air Temperature

*2、脉宽少于等于 100us, 占空比 1% Pulse width ≤ 100μs, Duty cycle= 1%

*3、离胶体 2mm 以上焊接 5s 内 2mm form body for 5 seconds

光电特性 Electro-Optical Characteristics

| 电性参数 (温度=25°C) Parameter (Ta=25°C) | | 符号 Symbol | 条件 Condition | 最小值 Min. | 典型值 Typ. | 最大值 Max. | 单位 Units |
|---------------------------------------|--|------------------------|--|-------------|-------------|-------------|-------------|
| 输入端 Input | 正向电压 Forward Voltage | V _F | I _F =20mA | -- | 1.2 | 1.6 | V |
| | 峰值波长 Peak Wavelength | λ _p | I _F =20mA | -- | 940 | -- | nm |
| | 反向电流 Reverse Current | I _R | V _R =5V | -- | -- | 10 | μA |
| 输出端 Output | 暗电流 Dark Current | I _{CEO} | Ee=0mW/cm ² V _{CE} =20V | -- | -- | 10 | uA |
| | 集电极-发射极的工作电压 C-E Saturation Voltage | V _{CE(SAT)} | I _C =2mA Ee=1mW/cm ² | -- | -- | 0.4 | V |
| 转换特性 Transfer Characteristics | 上升时间 Rise Time | t _r | V _{CE} =5V I _C =1mA | -- | 400 | -- | μS |
| | 下降时间 Fall Time | t _f | R _L =1000Ω | -- | 400 | -- | |
| | 光电流 Collector Current | I _{C(ON)} (5) | I _F =10mA V _{CE} =5V | 900 | -- | 1100 | uA |
| 1100 | | | | -- | 1300 | | |

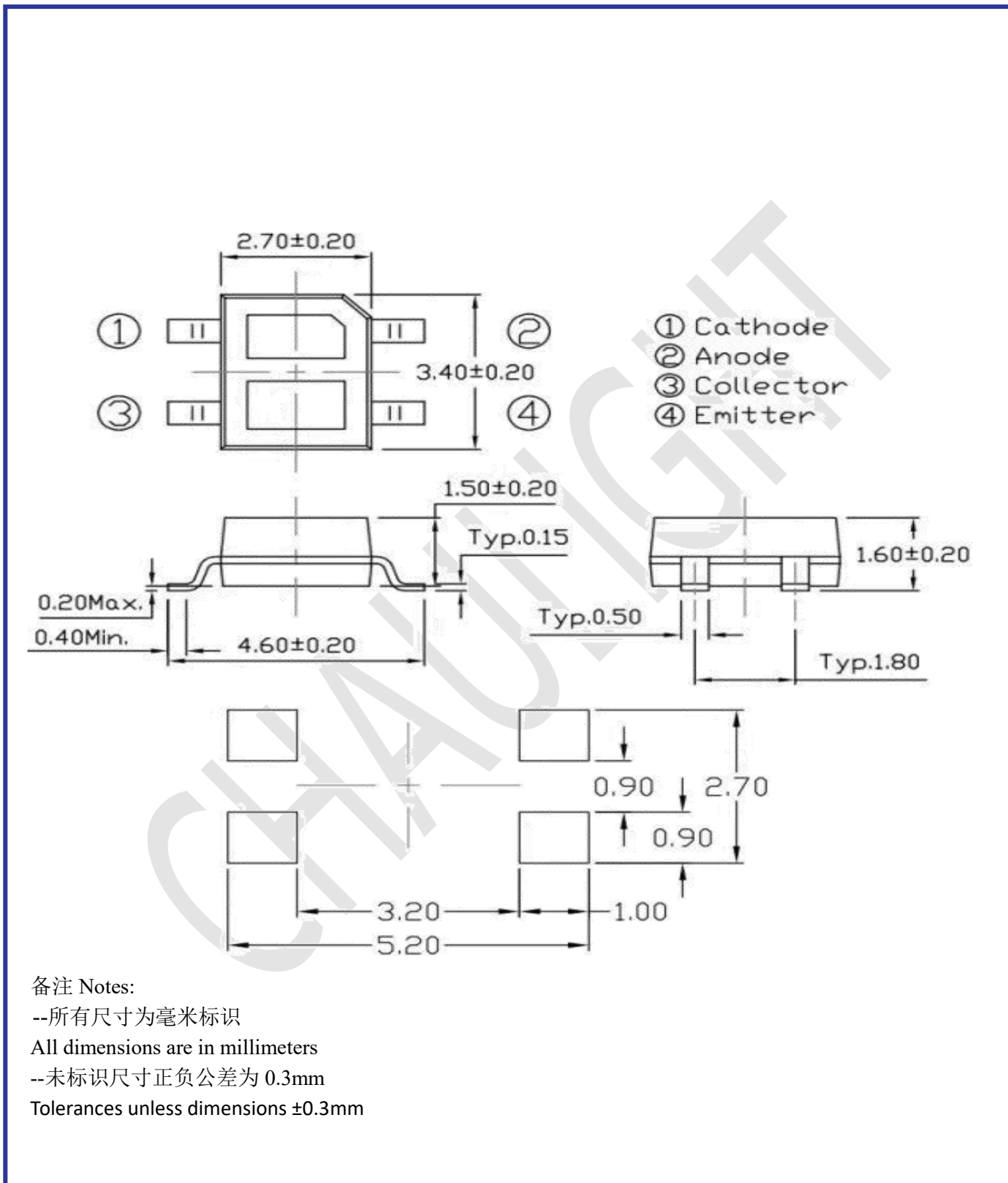
等级档位 Rank

| 档位 BIN | 符号 Symbol | 条件 Condition | 符合 Symbol | 范围 Ratings | 单位 Unit |
|--------|-----------|-----------------------|-----------|------------|---------|
| NA | Ic (on) | $V_{CE}=5V, I_F=10mA$ | 180 | 440 | μA |
| B1 BIN | Ic (on) | $V_{CE}=5V, I_F=10mA$ | 180 | 250 | μA |
| B2 BIN | Ic (on) | $V_{CE}=5V, I_F=10mA$ | 230 | 300 | μA |
| B BIN | Ic (on) | $V_{CE}=5V, I_F=10mA$ | 180 | 300 | μA |
| C BIN | Ic (on) | $V_{CE}=5V, I_F=10mA$ | 250 | 440 | μA |
| C2 BIN | Ic (on) | $V_{CE}=5V, I_F=10mA$ | 310 | 440 | μA |

备注 Notes:

--正向电压的测量公差是 $\pm 0.1V$ Measurement Uncertainty of Forward Voltage: $\pm 0.1V$ --发光强度的测量公差是 $\pm 10\%$ Measurement Uncertainty of Luminous Intensity: $\pm 10\%$ --峰值波长的测量公差是 $\pm 1.0nm$ Measurement Uncertainty of Dominant Wavelength $\pm 1.0nm$

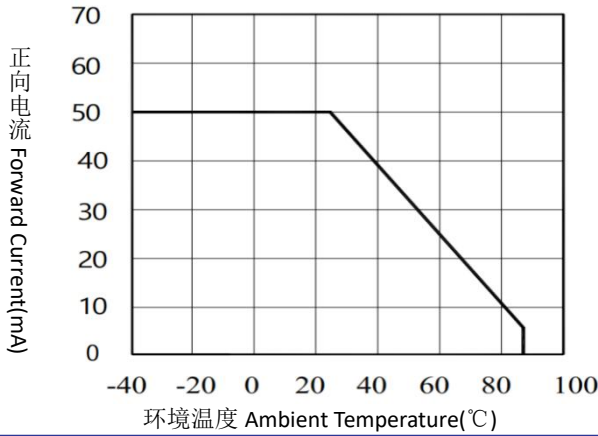
产品尺寸 Package Dimension



发射管特性曲线图 Typical Electro-Optical Characteristics Curves-IR

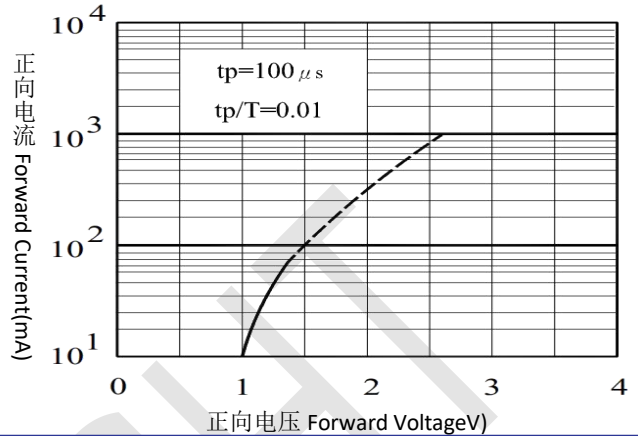
正向电流与环境温度的关系

Forward Current vs. Ambient Temperature



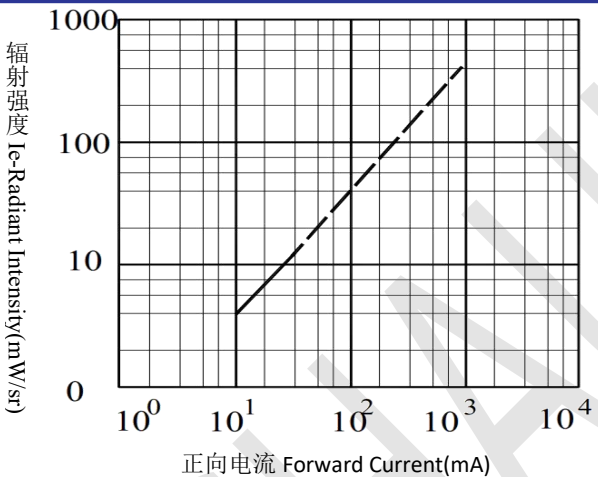
正向电流与正向电压的关系

Forward Current vs. Forward Voltage



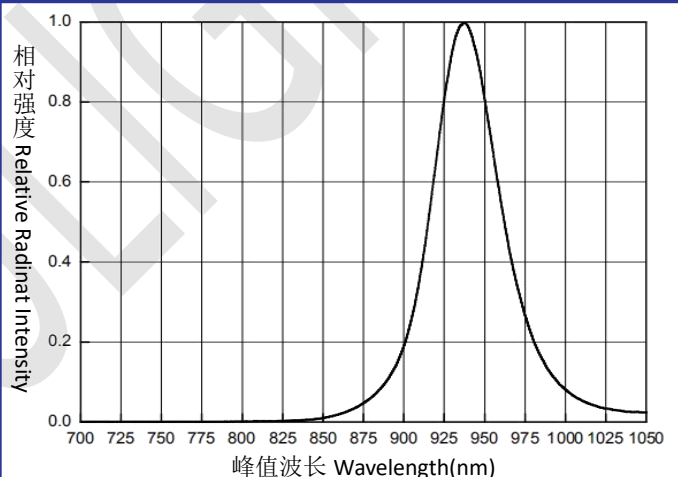
辐射强度与正向电流的关系

Radiant Intensity vs. Forward Current



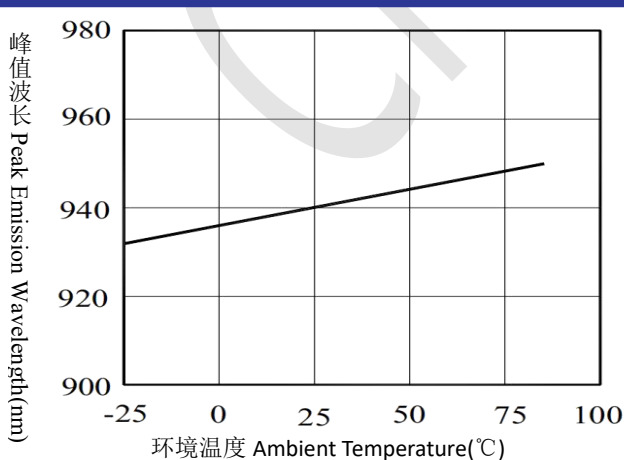
波长曲线图

Spectral Distribution



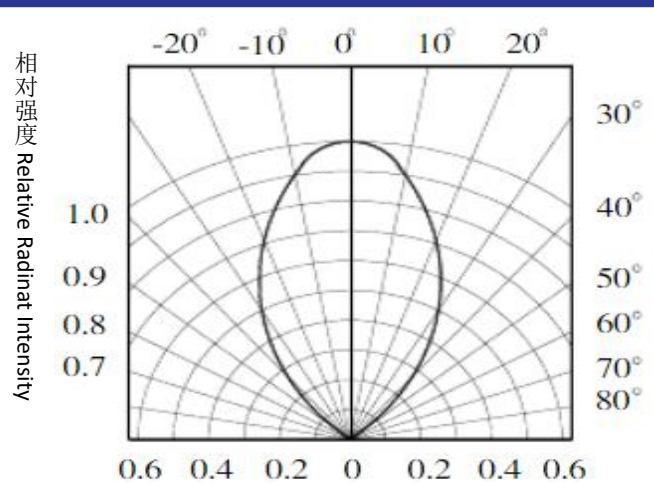
峰值波长与环境温度的关系

Peak Emission Wavelength vs. Ambient Temperature



相对辐射强度与角位移的关系

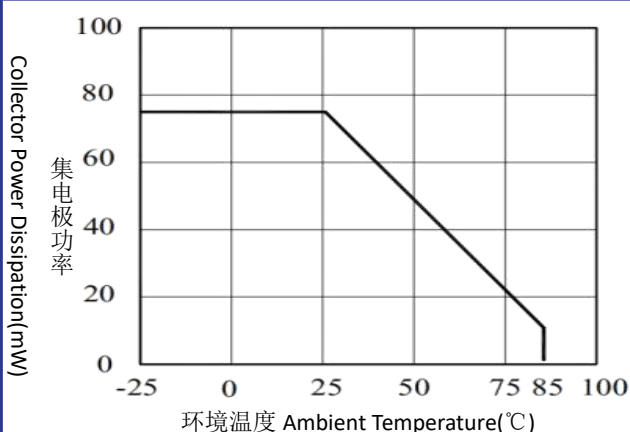
Relative Radiant Intensity vs. Angular Displacement



接收管特性曲线图 Typical Electro-Optical Characteristics Curves-PT

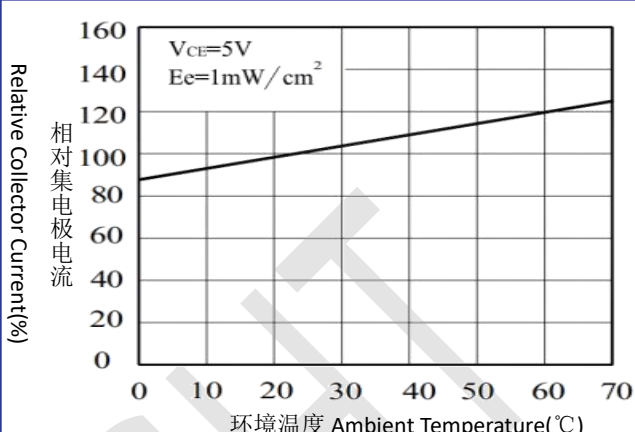
集电极功率与环境温度的关系

Collector Power Dissipation vs. Ambient Temperature



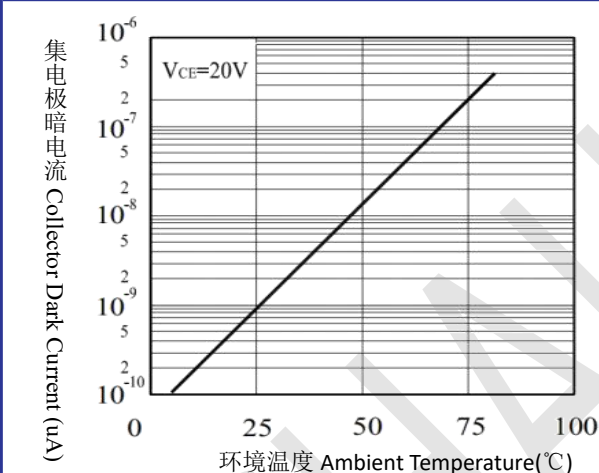
相对集电极电流与环境温度的关系

Relative Collector Current vs. Ambient Temperature



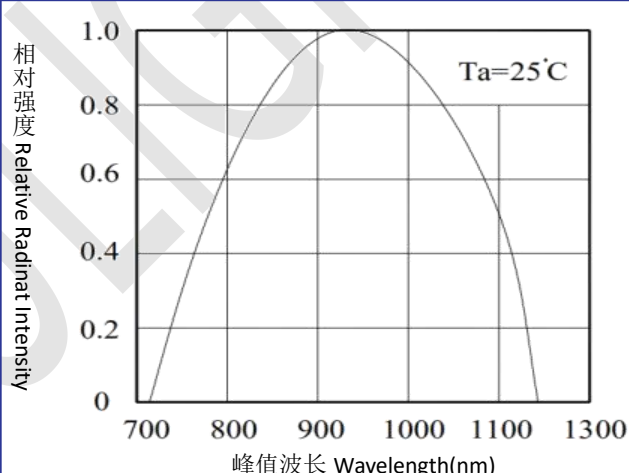
集电极暗电流与环境温度的关系

Collector Dark Current vs. Ambient Temperature



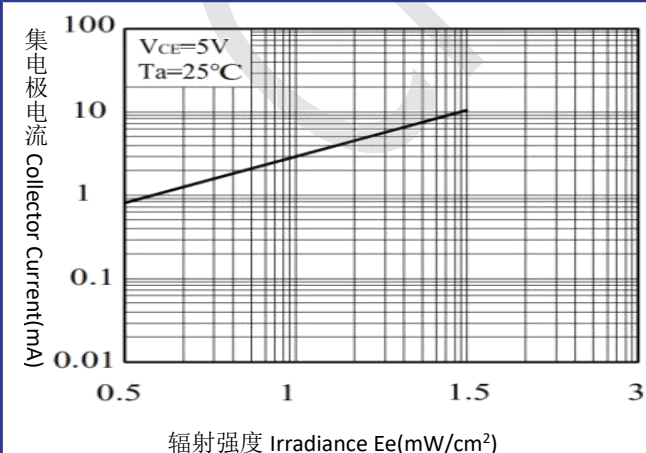
感应波长曲线图

Spectral Sensitivity



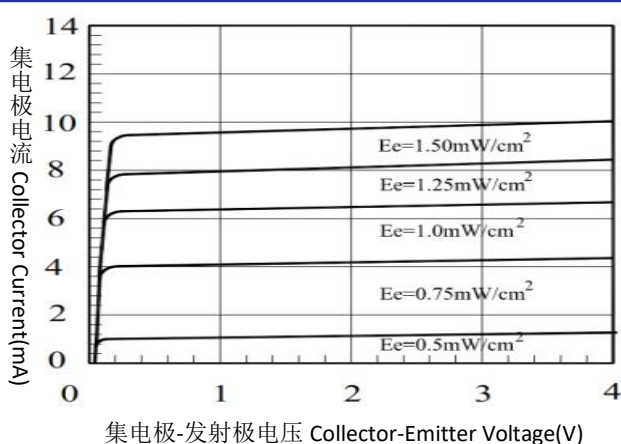
集电极电流与辐射强度的关系

Collector Current vs. Irradiance



集电极电流与集电极-发射极电压的关系

Collector Current vs. Collector-Emitter Voltage



光电开关特性曲线图 Typical Electro-Optical Characteristics Curves-ITR

光电流与感应距离之间的关系 Relative Collector Current vs Distance Between Sensor

Fig.1 Relative Collector Current vs. Distance between Sensor and Al Evaporation Galss

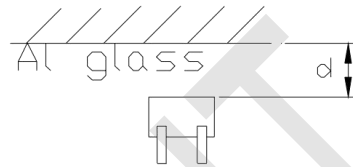
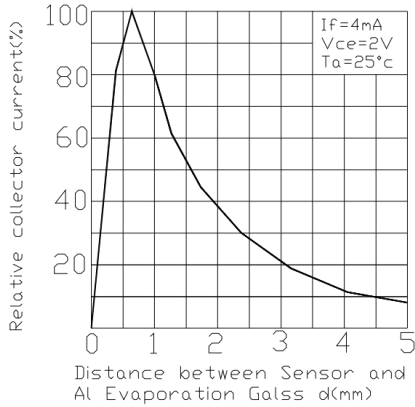


Fig.2 Relative Collector Current vs. Card Moving Distance (l)

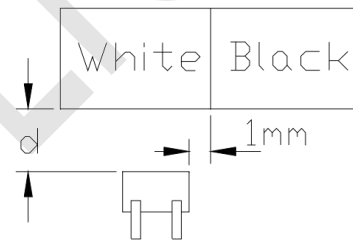
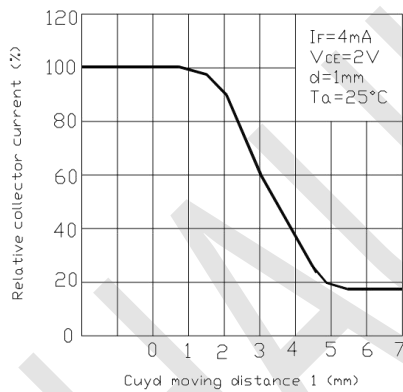
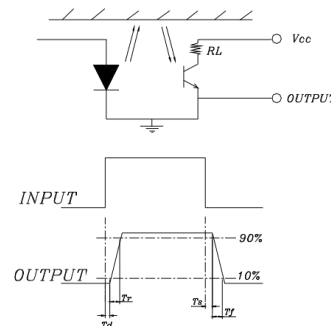
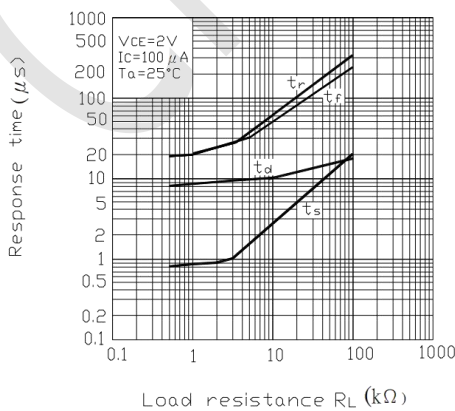
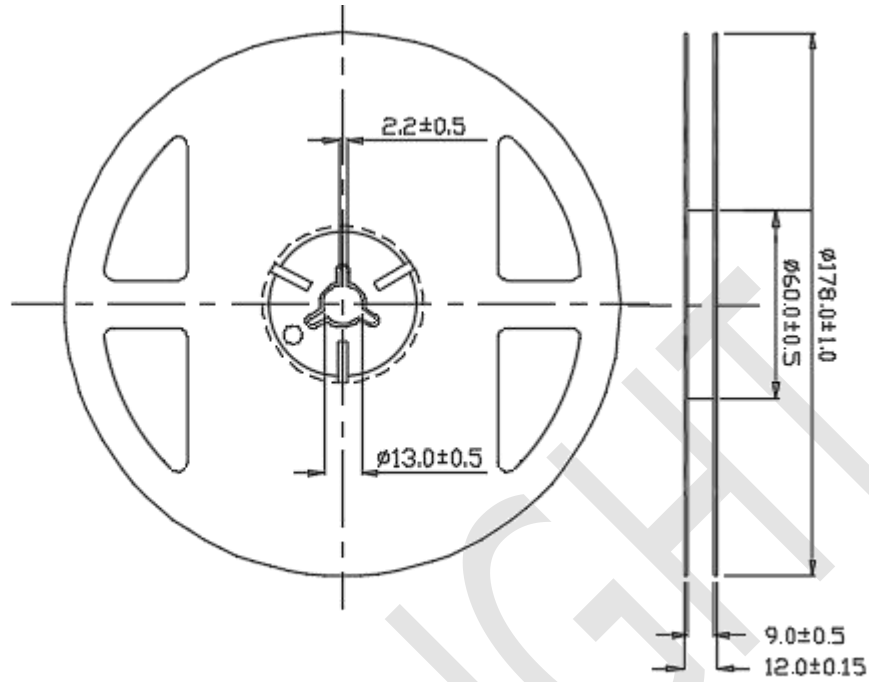


Fig.3 Response Time vs. Load Resistance

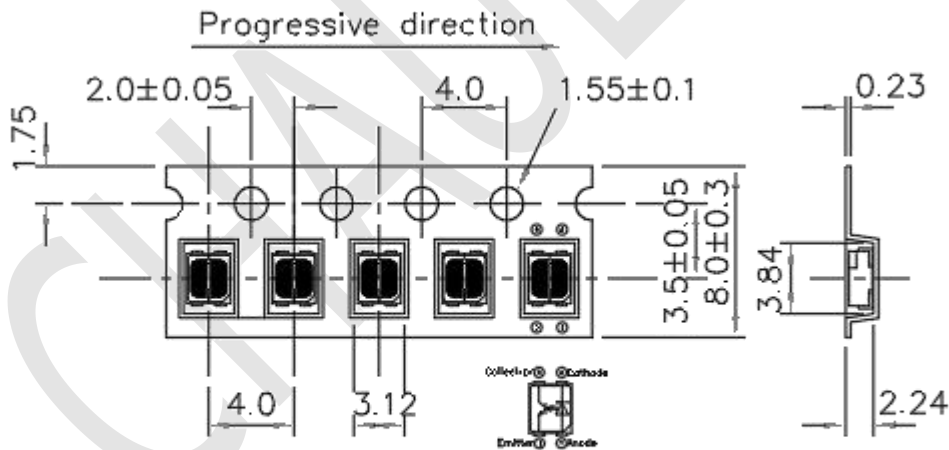


包装规格 Packing Specification



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Carrier Tape Dimensions:(Quantity: 2000pcs/reel)



TOLERANCES UNLESS DIMENSION ± 0.1
ANGLE ± 0.5
UNIT: mm

Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

注意事项 Note

--过流保护 Over-current-proof

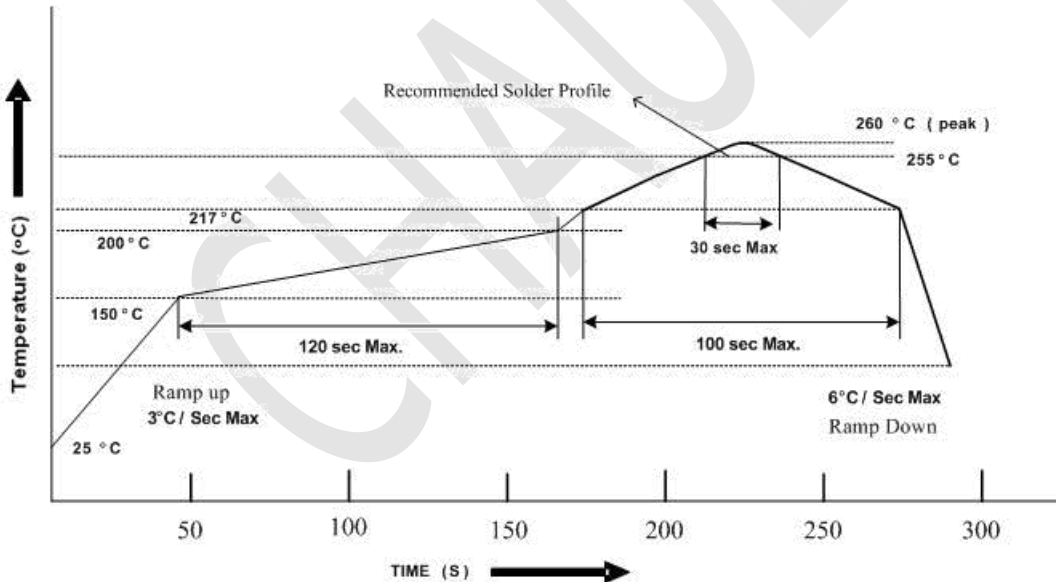
1、客户必须应用电阻进行保护，否则会造成轻微电压偏移大电流变化（烧毁将发生）。Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

--储存 Storage

- 1、产品准备使用前不要打开防潮袋。Do not open moisture proof bag before the products are ready to use.
- 2、在打开包装之前，二极管应保持在 10°C~30°C 和 90%RH 或以下。Before opening the package, the LED should be kept at 10°C~30°C and 90%RH or less.
- 3、二极管建议在一年内使用。The LED suggested be used within one year.
- 4、打开包装后，设备必须存储在 10°C~30°C 和 60%RH，并在 168 小时内使用（地板寿命）。如果未使用的二极管仍然存在，它应储存在防潮包装中。After opening the package, the devices must be stored at 10°C~30°C and 60%RH, and used within 168 hours (floor life). If unused LED remain, it should be stored in moisture proof packages.
- 5、如果吸湿材料（干燥剂材料）已褪色或未打开的袋子已超过保质期或设备（袋外）已超过地板寿命，需要烘焙处理。If the moisture absorbent material (desiccant material) has faded or unopened bag has exceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.
- 6、如果需要烘焙，请参阅 IPC/JEDECJ-STD-033 进行烘焙程序或建议以下条件：在 60°C ± 5°C 和 5%RH < 96 小时（筛/管/套单位）If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions: 96 hours at 60°C ± 5°C and < 5 % RH (reeled/tubed/loose units)

--焊接条件 Soldering Condition

- 1、铅焊料温度剖面 Lead solder temperature profile



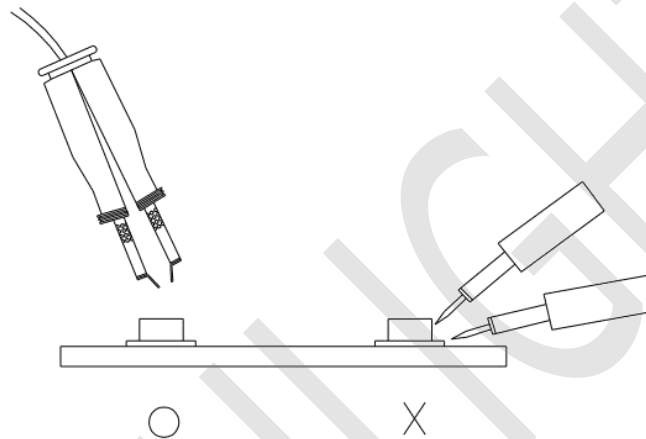
- 2、回流焊不应做两次以上。Reflow soldering should not be done more than two times.
- 3、焊接时，不要在加热过程中对 LED 施加压力。When soldering, do not put stress on the LEDs during heating.
- 4、焊接后，不要使电路板翘曲。After soldering, do not warp the circuit board.

--烙铁条件 Soldering Iron

每个端子都要去烙铁尖端温度低于 350°C 为 3 秒内一次少于烙铁容量 25W。离开两秒钟然后更多的间隔，并做焊接每个终端。手工焊料通常在开始的时候容易损坏产品。Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

--手工补数 Repairing

修理不应在 LED 焊接后进行。当修理是不可避免的是，应该使用双头烙铁（如下图所示）。应该是事先确认 LED 的特性是否会或不会损坏通过修理。Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

**--其他 Other**

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更改记录表 Engineering Change Notice-Record

| 版本 Edition | 更改日期 Date | 主要更改内容 Main Content | 拟制 Prepared | 确认 Checked |
|---------------|--------------|------------------------|----------------|---------------|
| A/0 | 2022-04-06 | 针对单一客户拟定规格 | 谢育国 | 郝三强 |
| | | | | |
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